



# SOT902-1

plastic extremely thin quad flat package; no leads; 8 terminals; UTLP based; body 1.6 x 1.6 x 0.5 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	XQFN8U
<b>Package type industry code</b>	XQFN8U
<b>Package style descriptive code</b>	XQFN (extremely thin quad flatpack; no leads)
<b>Package style suffix code</b>	U (UTLP based)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-255
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	14-11-2007

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.55	-	1.6	1.65	mm
E	package width	1.55	-	1.6	1.65	mm
A	seated height	[tbd]	-	[tbd]	0.5	mm
e	nominal pitch	-	-	0.55	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	8	-	



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## 2. Package outline

XQFN8U: plastic extremely thin quad flat package; no leads; 8 terminals; UTLP based; body 1.6 x 1.6 x 0.5 mm

SOT902-1

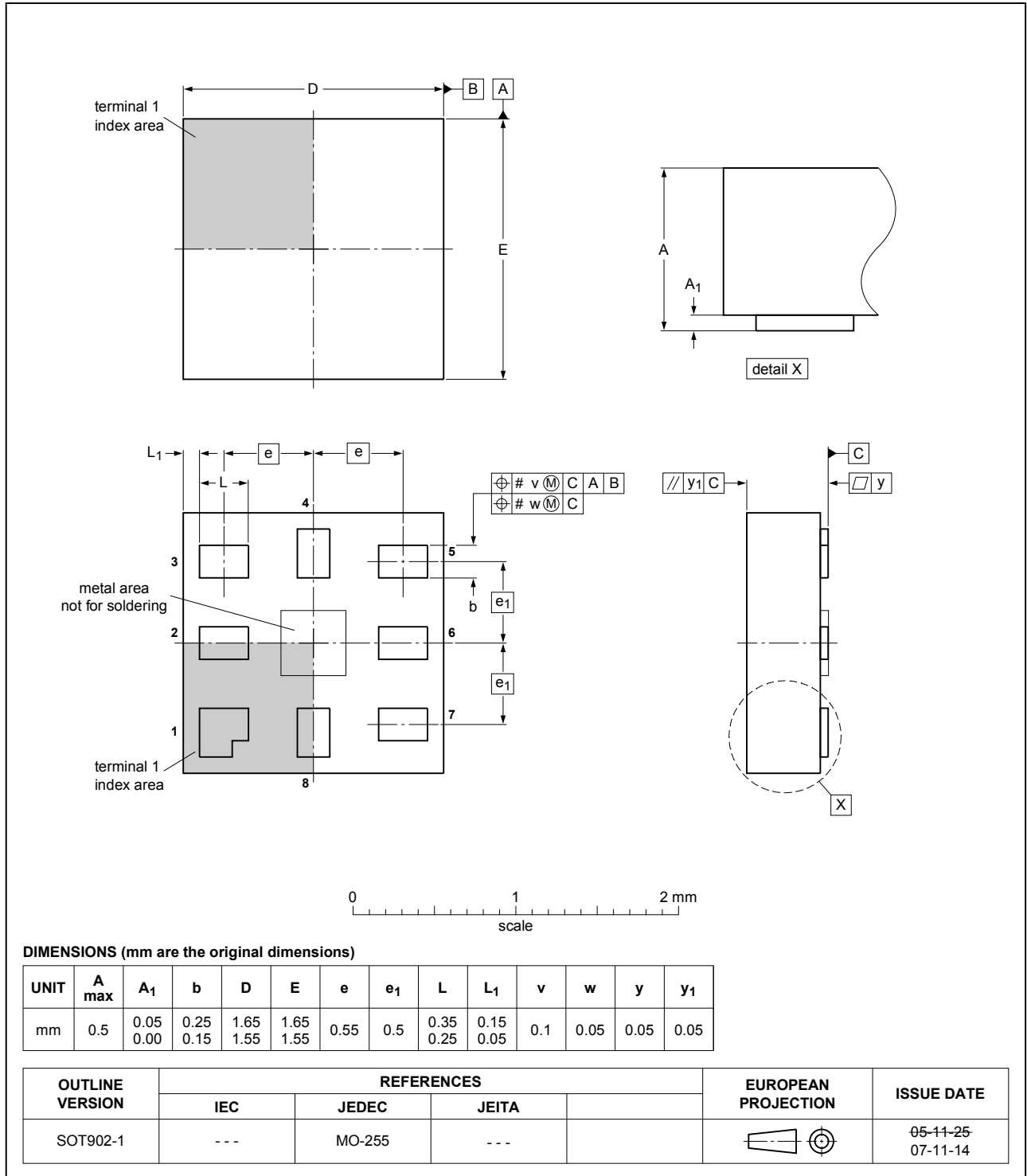
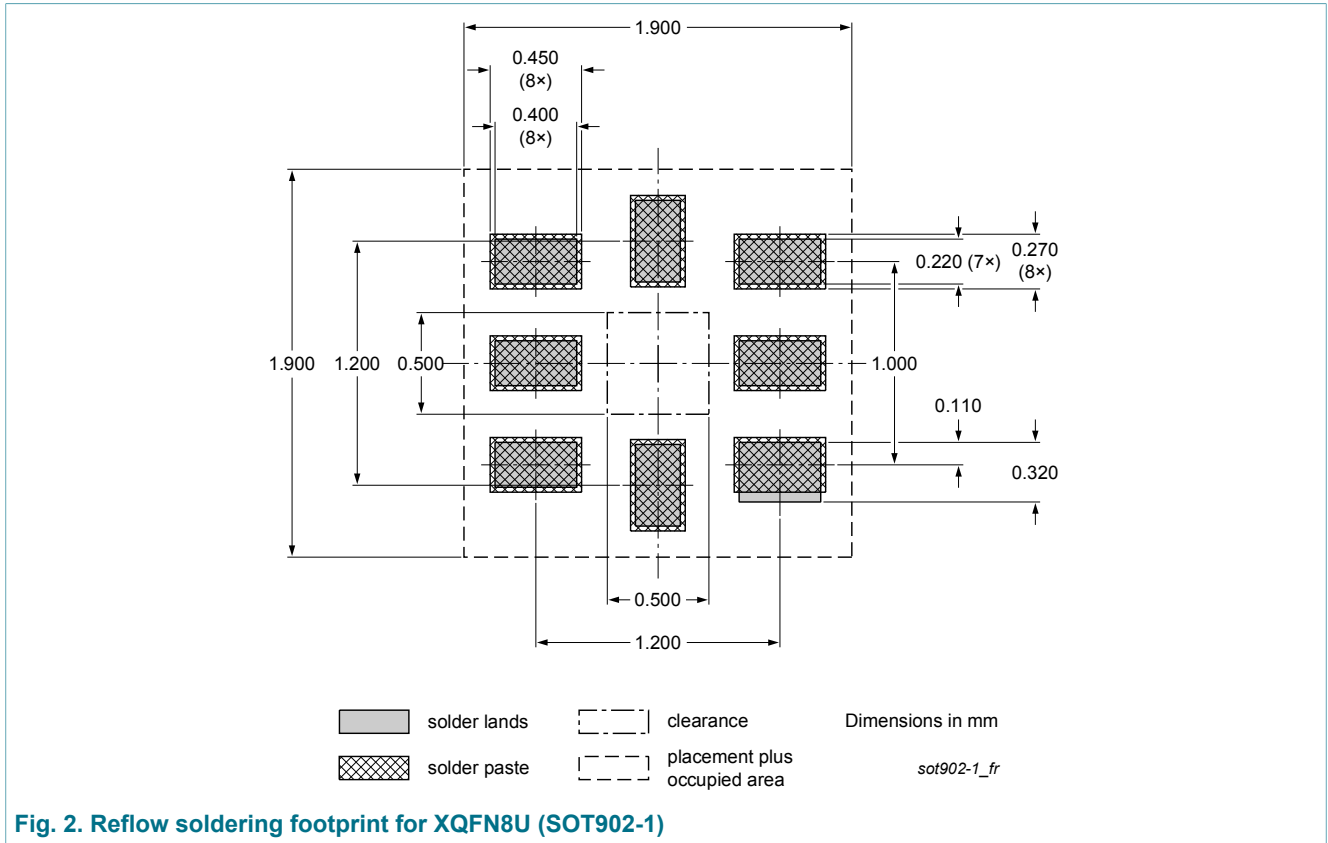


Fig. 1. Package outline XQFN8U (SOT902-1)

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### 3. Soldering



**Fig. 2. Reflow soldering footprint for XQFN8U (SOT902-1)**

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## 4. Legal information

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## 5. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Soldering.....	3
4. Legal information.....	4

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For sales office addresses, please send an email to: [salesaddresses@nxp.com](mailto:salesaddresses@nxp.com)  
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